

Materials List for:

# Micro-masonry for 3D Additive Micromanufacturing

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## Materials

Name	Company	Catalog Number	Comments
Az 5214	Clariant		1.5 mm thick Photoresist
Su8-100	Microchem		100 mm Photoresist used in mold
Sylgard 184	Dow Corning		PDMS mixed to fabricate stamp
Hydrofluoric acid	Honeywell		Acid to etch silicon oxide layer
Silicon on insulator	Ultrasil		Donor substrate was fabricated
Trichlorosilane	Sigma-Aldrich		Chemical used to help peeling of PDMS from mold